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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of Khandros, et al.

Application No. 08/984,615

Filed: December 3, 1997

For: SEMICONDUCTOR CHIP
ASSEMBLIES, METHODS OF

MAKING SAME AND COMPONENTS FOR SAME

Assistant Commissioner For Patents Washington, D.C. 20231

Group Art Unit: 2815

Examiner: S. Clark

Date: December 9, 1999

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RESPONSE

Madam:

This response is submitted in response to the Official Action mailed September 13, 1999, in which claims 61-76 were rejected.

REMARKS

This is submitted in response to the Official Action mailed September 13, 1999, in which claims 61-76 were rejected. Claims 61-76 were rejected under obviousness-type double patenting as being unpatentable over claim 18 of U.S. Patent In response, Applicants submit the enclosed No. 5,679,977. Terminal Disclaimer, disclaiming the term of any patent issuing on the instant application which would extend beyond the term of U.S. Patent No. 5,679,977. The assignee of U.S. No. 5,679,977, Tessera, Inc., is also the assignee for the The Terminal Declaimer is also in instant application. compliance with the other requirements of 37 C.F.R. $\S1.321(c)$. Applicants do not concede to the remarks set forth in the Official Action concerning this rejection.

Claims 72-73, 75 and 76 were rejected under obviousness-type double patenting as being unpatentable over claim 1 of the U.S. Patent No. 5,148,266. A Terminal Disclaimer disclaiming the term of any patent issuing on the instant application which would extend beyond the term of U.S. Patent No. 5,148,266 is also submitted herewith. The assignee of the

I hereby certify that this correspondance is being deposited with the United States Postal Service with sufficient postage as First Class mail in an envelope addressed to Assistant Commissioner for Patents, Washington, D.C. 20231 on December 9, 1999.

(Signature)

Marcus J. Millet

Typed or Printed Name of Person Signing Certificate

(C)

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